

## **Technical Data Sheet**

MODEL NO: S282ANB4

### Features:

●1.0x0.5mm SMT LED, 0.2mm thickness

● Compatible with automatic placement equipment

Compatible with reflow solder process

### Applications:

Indicators

Automotive : backlighting in dashboard and switch

Backlight for LCD

Dice material	Emitted color	Lens Color
InGaN	Blue	Water Clear

## Electrical/Optical Characteristics( $Ta=25^{\circ}C$ )

Parameter	Test	Symbol	Value			- Unit
	Condition		Min	Тур	Max	Offic
Dominant Wavelength	IF=20mA	λd		472		nm
Forward voltage	IF=20mA	VF	2.8		3.5	V
Luminous intensity	IF=20mA	lv	100	120		mcd
Viewing angle at 50% Iv	IF=10mA	2 <del>0</del> 1/2		120		Deg
Reverse current	VR=5V	IR			10	μА

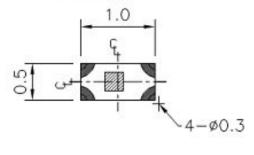


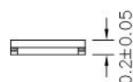
## Absolute Maximum Ratings(Ta=25°C)

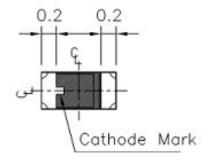
Parameter	Symbol	Value	Unit
Power dissipation	Pd	70	mW
Forward current	lf	20	mA
Reverse voltage	VR	5	V
Operating temperature range	Тор	-40 ~+80	$^{\circ}\!\mathbb{C}$
Storage temperature range	Tstg	-40 ~+85	$^{\circ}\!\mathbb{C}$
Peak pulsing current (1/8 duty f=1kHz)	IFP	125	mA

# PACKAGING DIMENSIONS (mm):

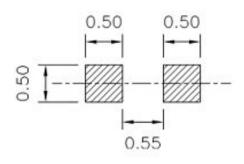
## Package outlines

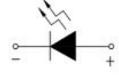






## Recommend Pad Layout





#### **Precautions For Use:**

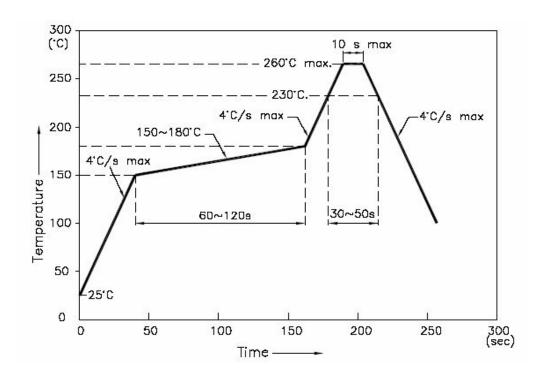
#### Over- current- proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)

### Storage

- 1. The operation of temperature and R.H. are :  $5^{\circ}$ C  $\sim 30^{\circ}$ C, 60%R.H. Max.
- 2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date).
- 3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is :  $60^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for 15hrs.

## ■ Reflow Temp/Time



#### NOTES:

- 1. We recommend the reflow temperature  $245\,^{\circ}\mathrm{C}(\pm 5\,^{\circ}\mathrm{C})$ .the maximum soldering temperature should be limited to  $260\,^{\circ}\mathrm{C}$ .
- 2. dont cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.



## ■Soldering iron

Basic spec is  $\leq$  5sec when 260°C. If temperature is higher, time should be shorter (+10°C  $\rightarrow$  -1sec ). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable. Surface temperature of the device should be under 230°C.

■ Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow \, solder etc.